


Full Material Declaration for attached parts list

Report generated: 04 December 2025, 14:44 GMT

| | |
|--|--|
|  | <p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p> |
|--|--|

Declaration effective from: 01 January 2021 [Approved on 04 December 2025, 14:44 GMT]

Materials and substances

| Use/Location | Material Group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|-------------------|---|-------------------------------|---|------------|------------------------------------|
| Chip (die) | Other inorganic materials | 1.3% | Silicon | 7440-21-3 | 100% |
| Die attach | Others (Rubber/non-thermoplastic Elastomer) | 0.05% | 4,4'-Sulfonylbisbenzamine | 80-08-0 | 4% |
| | | | Formaldehyde, polymer with (chloromethyl)oxirane and phenol | 9003-36-5 | 15% |
| Encapsulation | EP (Epoxy resin) | 53.19% | Silver | 7440-22-4 | 81% |
| | | | Carbon black | 1333-86-4 | 1% |
| | | | Silicon Dioxide | 7631-86-9 | 5% |
| | | | Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol | 29690-82-2 | 10% |
| Inner preparation | Copper (e.g. copper amounts in cable harnesses) | 1.09% | Fused Silica | 60676-86-0 | 84% |
| | | | Copper | 7440-50-8 | 100% |
| Leadfinish | Tin plating | 0.39% | Tin | 7440-31-5 | 100% |
| Leadframe | Copper (e.g. copper amounts in cable harnesses) | 43.98% | Copper | 7440-50-8 | 100% |

Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|----------------------------|------------------------|-----------|---------------|
| SOT-89 (IP) Pb & H-free_01 | Diode / Transistor SMD | 0.0537 | g |

